

Product Description

Shin-Etsu's KE-1833 is a single component, heat cure, high viscosity adhesive that will cure to form a tough, durable elastomer. KE-1833 has a pot life of 30 days at room temperature and exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- Excellent room-temperature stability
- Single component
- Heat cured
- High viscosity

Typical Applications

- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Addition
One/Two Component	One
Cold Storage	Y
Color	Reddish Brown
Density @ 23C (g/cm ³)	1.36
Viscosity (Pa·s)	140.00
Cure Conditions	1hr @ 120C
Working Time	30 Days
Shore A Hardness	33
Tensile Strength (MPa)	3.40
% Elongation	330
Shear Strength (MPa)	2.0
Volume Resistivity (TΩ·m)	2.0
Dielectric Strength (kV/mm)	25
Dielectric Constant	3.5 @ 50Hz
Dielectric Dissipation Factor	5x10 ⁻³ @ 50Hz
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

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